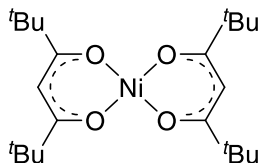


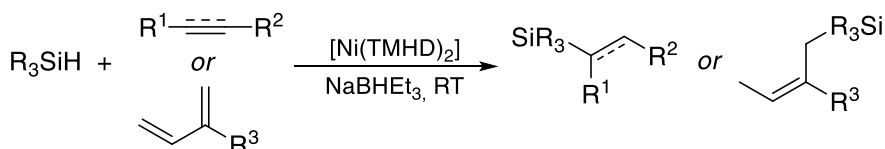
Catalog # 28-0088 Bis(2,2,6,6-tetramethyl-3,5-heptanedionato)nickel(II), min. 98% (99.9%-Ni) [Ni(TMHD)<sub>2</sub>]  
 Syn: Ni(DPM)<sub>2</sub>, Ni(THD)<sub>2</sub>



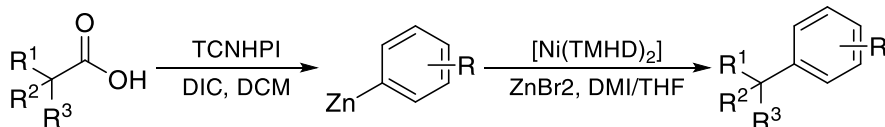
### Catalysis Applications

#### Technical Notes:

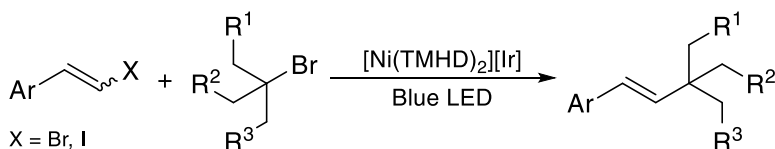
1. Catalyst for the hydrosilylation of 1,3-dienes, alkenes and alkynes
2. Used for Ni-catalyzed cross-coupling of tertiary carboxylic acids and (hetero)aryl zinc reagents
3. Used for Ir-co-catalyzed reductive cross-coupling of aryl vinyl halides and unactivated tertiary alkyl bromides
4. Used in dual Ni-/Pd-catalyzed reductive cross-coupling reactions between two phenol derivatives



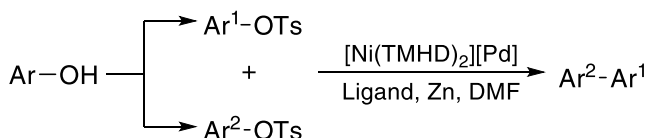
Tech Note (1)  
Ref. (1)



Tech Note (2)  
Ref. (2)



Tech Note (3)  
Ref. (3)



Tech Note (4)  
Ref. (4)

#### References:

1. [J. Organomet. Chem. 2016, 809, 57](#)
2. [Angew. Chem. Int. Ed. 2019, 58, 2454](#)
3. [Chem. Commun., 2019, 55, 5918](#)
4. [Org. Lett. 2020, 22, 6334](#)

### CVD/ALD Applications

#### Thermal Behavior:

- Sublimation: 120°C/0.02 Torr [1], 138°C/0.75 Torr [2], 125°C/0.01 Torr [3], 230/AP [4], ~190-200/AP [5]

- Melting point: 224-225°C [1]
- Decomposition: 362°C [2]
- TGA diagram and data is available in [5]
- Vapor pressure calculation is available in [6]

## Technical Notes:

1. ALD/CVD precursor and dopant for nickel thin film deposition

Target Deposit	Deposition Technique	Delivery Temperature	Pressure	Co-reactants	Deposition Temperature	Ref.
NiO <sub>x</sub>	ALD	165°C	5 Torr	H <sub>2</sub> O	275°C	7
Ni <sub>3</sub> N	CVD	160-170°C	5 Torr	NH <sub>3</sub>	200-290°C	8
NiS	ALD	165°C	1 Torr	H <sub>2</sub> S	170-350°C	9
LaNiO <sub>x</sub>	CVD	280°C (solv)	-	La(tmhd) <sub>3</sub> , O <sub>2</sub>	750°C	10
(Co <sub>1-x</sub> Ni <sub>x</sub> ) <sub>3</sub> O <sub>4</sub>	ALD	115°	0.75-2.25 Torr	Co(tmhd) <sub>2</sub> , O <sub>3</sub>	200°C	11

## References:

1. [Inorg. Chem. 1966, 5, 1200](#)
2. [Thermochimica Acta 2003, 404, 187](#)
3. [J. Alloys Comp. 2000, 308, 158](#)
4. [Ultrasonics Sonochem. 2003, 10, 95](#)
5. [Polyhedron 2007, 26, 4445](#)
6. [J. Chem. Eng. Data 2010, 55, 2149](#)
7. [Chem. Vap. Deposition 2009, 15, 186](#)
8. [ECS Trans. 2009, 25, 365](#)
9. [J. Vac. Sci. Technol. A, 2016, 34, 01A142](#)
10. [J. Electrochem. Soc. 2008, 155, P28](#)
11. [Dalton Trans., 2017, 46, 4796](#)